

## Excellent Integrated System Limited

Stocking Distributor

Click to view price, real time Inventory, Delivery & Lifecycle Information:

[Molex Connector Corporation](#)  
[0734153350](#)

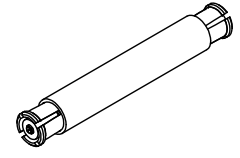
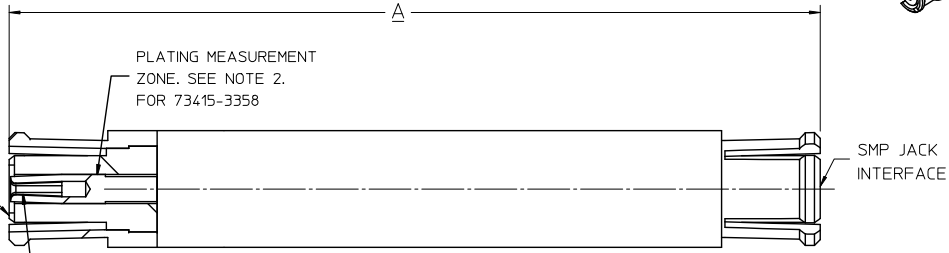
For any questions, you can email us directly:  
[sales@integrated-circuit.com](mailto:sales@integrated-circuit.com)

MATERIALS AND FINISHES:

BODY BERYLLIUM COPPER  
PLATED GOLD

CONTACT BERYLLIUM COPPER  
PLATED GOLD

INSULATOR TEFLON



NOTE 1: FOR 73415-3358  
GOLD PLATING THICKNESS MUST  
BE 10 MICRONS MINIMUM AT  
STATED LOCATION.

NOTE 2: FOR 73415-3358  
GOLD PLATING THICKNESS MUST  
BE 30 MICRONS MINIMUM AT  
STATED LOCATION.

73415-3356	PLACE 73415-3351 INTO SMALL TRAY
73415-3355	PLACE 73415-3350 INTO SMALL TRAY
PART NO.	DESCRIPTION

73415-3359	.646 REF	16.40 REF
73415-3358	.677 REF	17.20 REF
73415-3357	.449 REF	11.40 REF
73415-3354	1.131 REF	28.73 REF
73415-3353	.571 REF	14.50 REF
73415-3352	.520 REF	13.21 REF
73415-3351	.799 REF	20.30 REF
73415-3350	.937 REF	23.80 REF
PART NO.	IN	MM

PS-89675-3320	PRODUCT SPECIFICATION
MIL-STD-348A, FIG. 326.1	INTERFACE
SPECIFICATION	DESCRIPTION

CHG: ADDED NOTE 1 & NOTE 2 EC NO: URF2009-0237 DRAWN BY: 2008/11/05 CHKD: 2008/11/11 APPR: HUANG 2008/11/11 DESCRIPTION:	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM/IN		SCALE	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± --- ± --- 1 PLACE ± --- ± --- ANGULAR ± 2 °	DRAWN BY: TEF DATE: 2001/05/22 CHECKED BY: SSS DATE: 2001/05/22 APPROVED BY: GMH DATE: 2001/05/22	TITLE: SMP JACK TO JACK ADAPTER 50 OHMS SMP-J/J/ADP		MATERIAL NO. SEE TABLE DOCUMENT NO. SD-73415-335		MOLEX INCORPORATED		SHEET NO. 1 OF 1
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								